SN74AUP2G14 Low-Power Dual Schmitt-Trigger Inverter

1 Features

- Available in the Texas Instruments NanoStar™ package
- Low static-power consumption (I_{CC} = 0.9µA maximum)
- Low dynamic-power consumption (C_{pd} = 4.3pF typical at 3.3V)
- Low input capacitance (C_i = 1.5pF typical)
- Low noise – overshoot and undershoot <10% of V_{CC}
- I_{off} supports partial-power-down mode operation
- Wide operating V_{CC} range of 0.8V to 3.6V
- Optimized for 3.3V operation
- 3.6V I/O tolerant to support mixed-mode signal Operation
- t_{pd} = 4.3ns maximum at 3.3V
- Suitable for point-to-point applications
- Latch-up performance exceeds 100mA Per JESD 78, Class II
- ESD performance tested per JESD 22
  - 2000V human-body model (A114-B, Class II)
  - 1000V charged-device model (C101)

2 Applications

- Body control modules
- Engine control modules
- Servers and high-performance computing
- EPOS, ECR, and cash drawer
- Routers
- Desktop PC

3 Description

The AUP family is TI's premier solution to the industry's low-power needs in battery-powered portable applications. This family ensures a very low static- and dynamic-power consumption across the entire V_{CC} range of 0.8V to 3.6V, resulting in increased battery life (see Figure 5-1). This product also maintains excellent signal integrity (see the very low undershoot and overshoot characteristics shown in Figure 5-2).

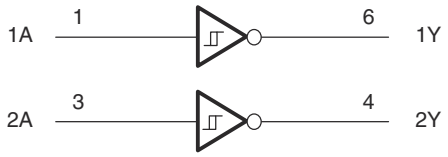
The SN74AUP2G14 contains two inverters and performs the Boolean function $Y = \overline{A}$. The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

NanoStar™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

Device Information

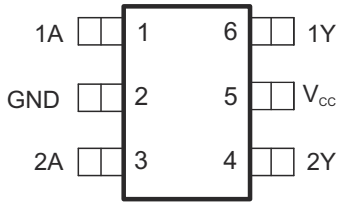
PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74AUP2G14DCK	SC70 (6)	2.00mm × 1.25mm
SN74AUP2G14DRY	SON (6)	1.45mm × 1.00mm
SN74AUP2G14DSF	SON (6)	1.00mm × 1.00mm
SN74AUP2G14YFP	DSBGA (6)	1.00mm × 1.40mm



Logic Diagram (Positive Logic)

Table of Contents

4 Pin Configuration and Functions



See mechanical drawings for dimensions.

Figure 4-1. DCK Package 6 -Pin SC70 Top View

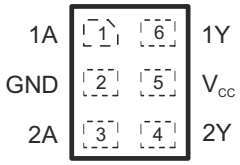


Figure 4-2. DRY Package 6-Pin USON Top View

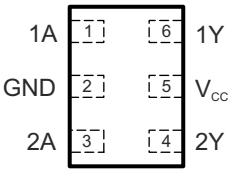


Figure 4-3. DSF Package 6-Pin X2SON Top View

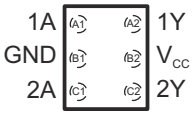


Figure 4-4. YFP Package 6-Pin DSBGA Top View

Table 4-1. Pin Functions

PIN					I/O	DESCRIPTION
NAME	DCK	DRY	DSF	YFP		
1A	1	1	1	A1	II	Gate 1 logic signal
GND	2	2	2	B1	—	Ground
2A	3	3	3	C1	I	Gate 2 logic signal
1Y	6	6	6	A2	O	Gate 1 inverted signal
V_{CC}	5	5	5	B2	—	Supply/Power Pin
2Y	4	4	4	C2	O	Gate 2 inverted signal

5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		–0.5	4.6	V
V_I	Input voltage (2)		–0.5	4.6	V
V_O	Voltage range applied to any output in the high-impedance or power-off state(2)		–0.5	4.6	V
V_O	Output voltage range in the high or low state(2)		–0.5	V_{CC} + 0.5	V
I_{IK}	Input clamp current	V_I < 0		–50	mA
I_{OK}	Output clamp current	V_O < 0		–50	mA
I_O	Continuous output current			±20	mA
	Continuous current through V_{CC} or GND			±50	mA
T_{stg}	Storage temperature		–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	±1000	

(1) JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

5.3 Recommended Operating Conditions

See (1)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		0.8	3.6	V
V_I	Input voltage		0	3.6	V
V_O	Output voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 0.8V		–20	µA
		V_{CC} = 1.1V		–1.1	mA
		V_{CC} = 1.4V		–1.7	
		V_{CC} = 1.65V		–1.9	
		V_{CC} = 2.3V		–3.1	
		V_{CC} = 3V		–4	
I_{OL}	Low-level output current	V_{CC} = 0.8V		20	µA
		V_{CC} = 1.1V		1.1	mA
		V_{CC} = 1.4V		1.7	
		V_{CC} = 1.65V		1.9	
		V_{CC} = 2.3V		3.1	
		V_{CC} = 3V		4	
T_A	Operating free-air temperature		–40	85	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. See *Implications of Slow or Floating CMOS Inputs* .

5.4 Thermal Information

THERMAL METRIC(1)		SN74AUP2G14				UNIT
		DRY (SON)	DSF (SON)	YFP (DSBGA)	DCK (SC70)	
		PINS	PINS	PINS	PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	234	300	132	252	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

5.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	T_A = 25°C			T_A = –40°C to 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	
V_{T+} Positive-going input threshold voltage		0.8V	0.3		0.6	0.3	0.6	V
		1.1V	0.53		0.9	0.53	0.9	
		1.4V	0.74		1.11	0.74	1.11	
		1.65V	0.91		1.29	0.91	1.29	
		2.3V	1.37		1.77	1.37	1.77	
		3V	1.88		2.29	1.88	2.29	
$V_{T–}$ Negative-going input threshold voltage		0.8V	0.1		0.6	0.1	0.6	V
		1.1V	0.26		0.65	0.26	0.65	
		1.4V	0.39		0.75	0.39	0.75	
		1.65V	0.47		0.84	0.47	0.84	
		2.3V	0.69		1.04	0.69	1.04	
		3V	0.88		1.24	0.88	1.24	
ΔV_T Hysteresis ($V_{T+} – V_{T–}$)		0.8V	0.07		0.5	0.07	0.5	V
		1.1V	0.08		0.46	0.08	0.46	
		1.4V	0.18		0.56	0.18	0.56	
		1.65V	0.27		0.66	0.27	0.66	
		2.3V	0.53		0.92	0.53	0.92	
		3V	0.79		1.31	0.79	1.31	
V_{OH}	I_{OH} = –20µA	0.8V to 3.6V	V_{CC} – 0.1			V_{CC} – 0.1		V
	I_{OH} = –1.1mA	1.1V	0.75 × V_{CC}			0.7 × V_{CC}		
	I_{OH} = –1.7mA	1.4V	1.11			1.03		
	I_{OH} = –1.9mA	1.65V	1.32			1.3		
	I_{OH} = –2.3mA	2.3V	2.05			1.97		
	I_{OH} = –3.1mA		1.9			1.85		
	I_{OH} = –2.7mA	3V	2.72			2.67		
	I_{OH} = –4mA		2.6			2.55		
V_{OL}	I_{OL} = 20µA	0.8 V to 3.6V			0.1		0.1	V
	I_{OL} = 1.1mA	1.1V			0.3 × V_{CC}		0.3 × V_{CC}	
	I_{OL} = 1.7mA	1.4V			0.31		0.37	
	I_{OL} = 1.9mA	1.65V			0.31		0.35	
	I_{OL} = 2.3mA	2.3V			0.31		0.33	
	I_{OL} = 3.1mA				0.44		0.45	
	I_{OL} = 2.7mA	3V			0.31		0.33	
	I_{OL} = 4mA				0.44		0.45	
I_I A or B input	V_I = GND to 3.6V	0V to 3.6V			0.1		0.5	µA
I_{off}	V_I or V_O = 0V to 3.6V	0V			0.2		0.6	µA
ΔI_{off}	V_I or V_O = 0V to 3.6V	0V to 0.2V			0.2		0.6	µA
I_{CC}	V_I = GND or (V_{CC} to 3.6V), I_O = 0	0.8V to 3.6V			0.5		0.9	µA
ΔI_{CC}	V_I = V_{CC} – 0.6V(1), I_O = 0	3.3V			40		50	µA
C_i	V_I = V_{CC} or GND	0V		1.5				pF
		3.6V		1.5				
C_o	V_O = GND	0V		3				pF

(1) One input at V_{CC} – 0.6V, other input at V_{CC} or GND.

5.6 Switching Characteristics

over recommended operating free-air temperature range, Switching Characteristics: C_L = 5pF (unless otherwise noted) (see Figure 6-3 and Figure 6-4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8V		18				ns
			1.2V ± 0.1V	2.6	7.3	12.8	2.1	15.6	
			1.5V ± 0.1V	1.4	5.2	8.7	0.9	10.3	
			1.8V ± 0.15V	1	4.2	6.6	0.5	8.2	
			2.5V ± 0.2V	1	3	4.4	0.5	5.5	
			3.3V ± 0.3V	1	2.4	3.5	0.5	4.3	

5.7 Switching Characteristics

over recommended operating free-air temperature range, Switching Characteristics C_L = 10pF (unless otherwise noted) (see Figure 6-3 and Figure 6-4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8V		18.4				ns
			1.2V ± 0.1V	4.6	7.9	13.4	1.3	16.7	
			1.5V ± 0.1V	4	6	9.6	2.2	11.8	
			1.8V ± 0.15V	3.6	5	7.9	2.4	9.5	
			2.5V ± 0.2V	3.2	4	5.5	2.3	6.8	
			3.3V ± 0.3V	2.9	3.5	4.6	2.1	5.6	

5.8 Switching Characteristics

over recommended operating free-air temperature range, Switching Characteristics C_L = 15pF (unless otherwise noted) (see Figure 6-3 and Figure 6-4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8V		24				ns
			1.2V ± 0.1V	3.6	9.9	16.3	3.1	19.9	
			1.5V ± 0.1V	2.3	7.2	11.1	1.8	13.2	
			1.8V ± 0.15V	1.6	5.8	8.7	1.1	10.6	
			2.5V ± 0.2V	1	4.3	5.9	0.5	7.3	
			3.3V ± 0.3V	1	3.4	4.8	0.5	5.9	

5.9 Switching Characteristics

over recommended operating free-air temperature range, Switching Characteristics C_L = 30pF (unless otherwise noted) (see Figure 6-3 and Figure 6-4)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	T_A = 25°C			T_A = –40°C to 85°C		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	0.8V		32.8				ns
			1.2V ± 0.1V	4.9	13.1	20.9	4.4	25.5	
			1.5V ± 0.1V	3.4	9.5	14.2	2.9	16.9	
			1.8V ± 0.15V	2.5	7.7	11	2	13.5	
			2.5V ± 0.2V	1.8	5.7	7.6	1.3	9.4	
			3.3V ± 0.3V	1.5	4.7	6.2	1	7.5	

5.10 Operating Characteristics

T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	f = 10MHz	0.8V	4	pF
			1.2V ± 0.1V	4	
			1.5V ± 0.1V	4	
			1.8V ± 0.15V	4	
			2.5V ± 0.2V	4.1	
			3.3V ± 0.3V	4.3	

5.11 Typical Characteristics

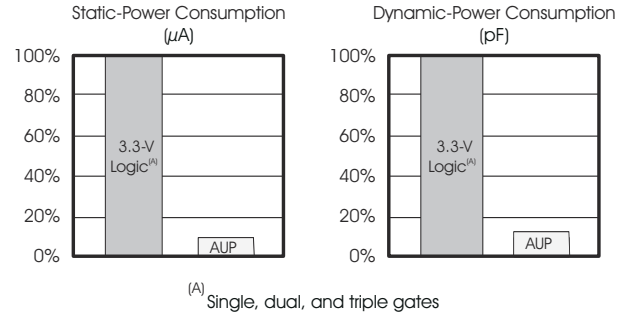


Figure 5-1. AUP – The Lowest-Power Family

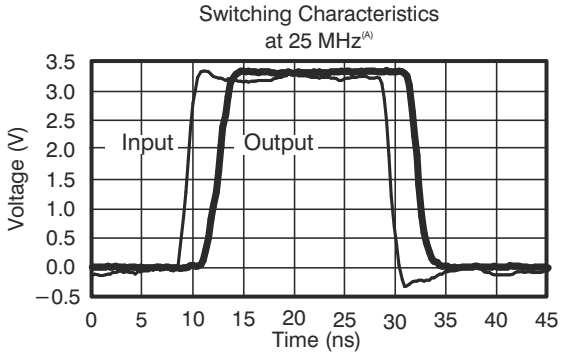
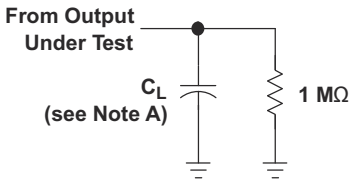


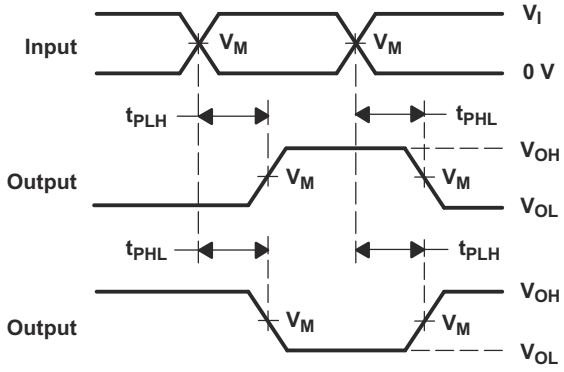
Figure 5-2. Excellent Signal Integrity

6 Parameter Measurement Information

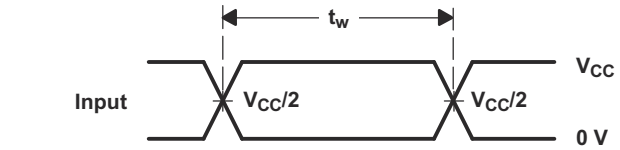


LOAD CIRCUIT

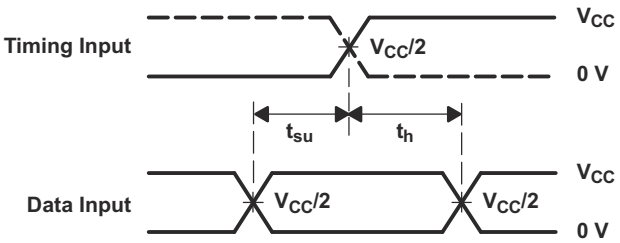
	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



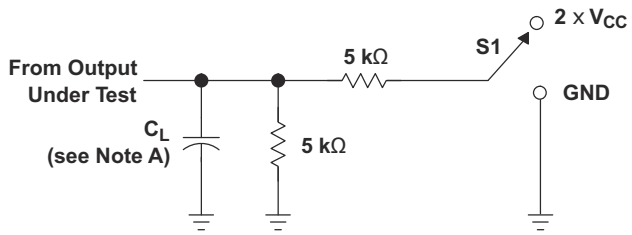
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10MHz, Z_O = 50Ω, for propagation delays t_r/t_f = 3ns, for setup and hold times and pulse width t_r/t_f = 1.2ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLH} and t_{PHL} are the same as t_{pd}.
F. All parameters and waveforms are not applicable to all devices.

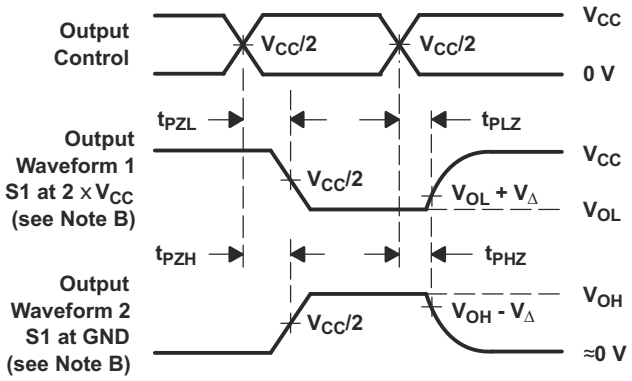
Figure 6-1. Load Circuit and Voltage Waveforms



LOAD CIRCUIT

TEST	S1
t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	2 × V_{CC} GND

	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_Δ	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V

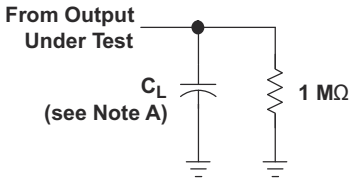


VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10MHz, Z_O = 50Ω, t_r/t_f = 3ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PLH} and t_{PHL} are the same as t_{pd}.
G. All parameters and waveforms are not applicable to all devices.

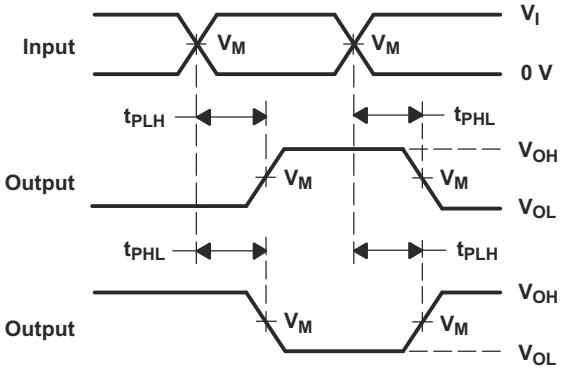
Figure 6-2. Load Circuit and Voltage Waveforms

6.1 Propagation Delays, Setup and Hold Times, and Pulse Width

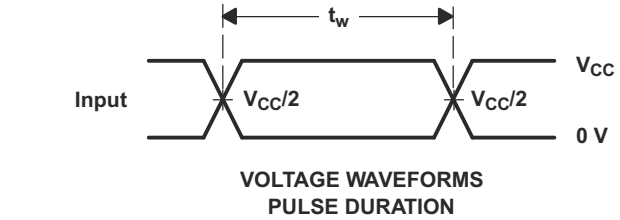


LOAD CIRCUIT

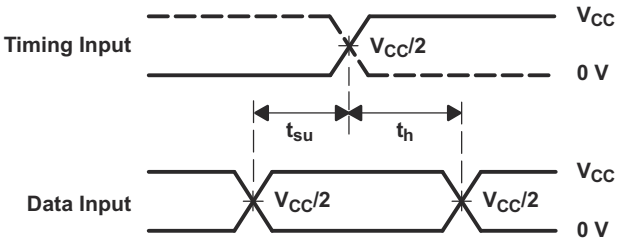
	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
PULSE DURATION

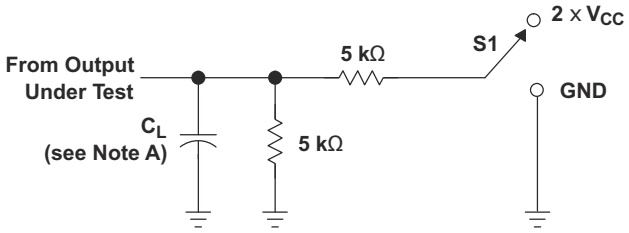


VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, for propagation delays t_r/t_f = 3 ns, for setup and hold times and pulse width t_r/t_f = 1.2 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLH} and t_{PHL} are the same as t_{pd}.
F. All parameters and waveforms are not applicable to all devices.

Figure 6-3. Load Circuit and Voltage Waveforms

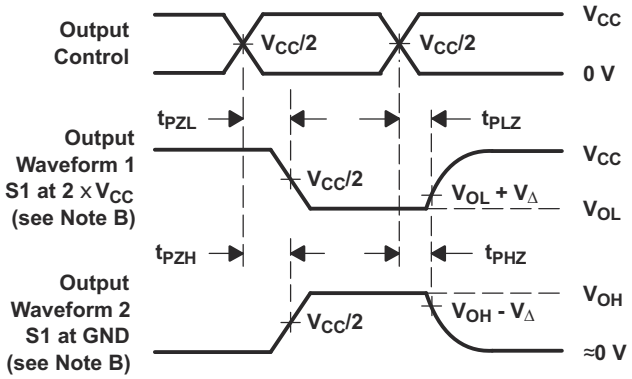
6.2 Enable and Disable Times



TEST	S1
t_{PLZ}/t_{PZL} t_{PHZ}/t_{PZH}	2 × V_{CC} GND

LOAD CIRCUIT

	V_{CC} = 0.8 V	V_{CC} = 1.2 V ± 0.1 V	V_{CC} = 1.5 V ± 0.1 V	V_{CC} = 1.8 V ± 0.15 V	V_{CC} = 2.5 V ± 0.2 V	V_{CC} = 3.3 V ± 0.3 V
C_L	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF	5, 10, 15, 30 pF
V_M	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$
V_I	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}	V_{CC}
V_Δ	0.1 V	0.1 V	0.1 V	0.15 V	0.15 V	0.3 V



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r/t_f = 3 ns.
D. The outputs are measured one at a time, with one transition per measurement.
E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
F. t_{PLH} and t_{PHL} are the same as t_{pd}.
G. All parameters and waveforms are not applicable to all devices.

Figure 6-4. Load Circuit and Voltage Waveforms

7 Detailed Description

7.1 Overview

The SN74AUP2G14 contains two inverters and performs the Boolean function Y = A. The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positivegoing (VT+) and negative-going (VT–) signals.

This device is fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

7.2 Functional Block Diagram

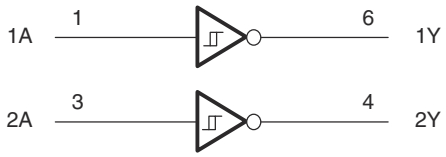


Figure 7-1. Logic Diagram (Positive Logic)

7.3 Feature Description

As the inputs are 5.5V tolerant, the device can be used as a down translator. When the input voltage exceeds VT+ (Max), the output will follow VCC, performing down-translation if the input voltage exceeds VCC.

7.4 Device Functional Modes

Table 7-1 lists the functional modes of SN74AUP2G14.

Table 7-1. Function Table (Each Inverter)

INPUT A	OUTPUT Y
H	L
L	H

8 Application and Implementation

Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes, as well as validating and testing their design implementation to confirm system functionality.

8.1 Application Information

The SN74AUP2G14 contains two inverters and performs the Boolean function $Y = \overline{A}$. The device functions as two independent inverters, but because of Schmitt action, it may have different input threshold levels for positive-going (V_{T+}) and negative-going (V_{T-}) signals.

8.2 Typical Application

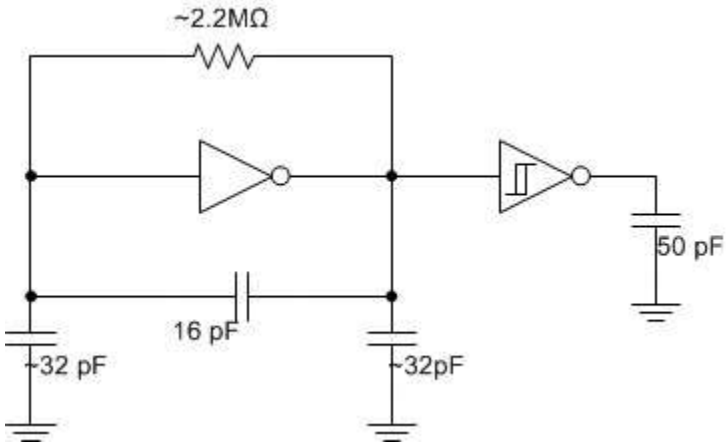


Figure 8-1. Typical Application Schematic

8.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so routing and load conditions should be considered to prevent ringing.

8.2.2 Detailed Design Procedure

1. Recommended Input Conditions
   - Rise time and fall time specs. See (Δt/ΔV) in the *Section 5.3* table.
   - Specified high and low levels. See (V_{IH} and V_{IL}) in the *Section 5.3* table.
   - Inputs are overvoltage tolerant allowing them to go as high as (V_I max) in the *Section 5.3* table at any valid V_{CC} .
2. Recommend Output Conditions
   - Load currents should not exceed (I_O max) per output and should not exceed (continuous current through V_{CC} or GND) total current for the part. These limits are located in the *Section 5.1* table.
   - Outputs should not be pulled above V_{CC}.

8.3 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the table. Each VCC pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1µF capacitor. If there are multiple VCC pins, then TI recommends a 0.01µF or 0.022µF capacitor for each power pin. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. 0.1µF and 1µF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

8.4 Layout

8.4.1 Layout Guidelines

- Bypass capacitor placement
  - Place near the positive supply terminal of the device
  - Provide an electrically short ground return path
  - Use wide traces to minimize impedance
  - Keep the device, capacitors, and traces on the same side of the board whenever possible
- Signal trace geometry
  - 8mil to 12mil trace width
  - Lengths less than 12cm to minimize transmission line effects
  - Avoid 90° corners for signal traces
  - Use an unbroken ground plane below signal traces
  - Flood fill areas around signal traces with ground
  - Parallel traces must be separated by at least 3x dielectric thickness
  - For traces longer than 12cm
    - Use impedance controlled traces
    - Source-terminate using a series damping resistor near the output
    - Avoid branches; buffer each signal that must branch separately

8.4.2 Layout Example

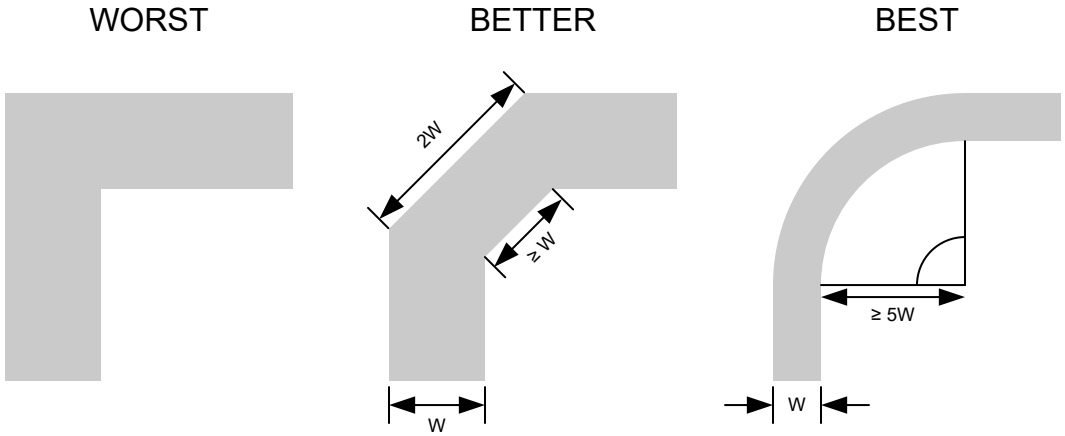


Figure 8-2. Example Trace Corners for Improved Signal Integrity

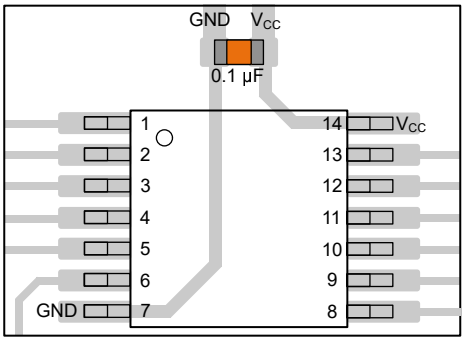


Figure 8-3. Example Bypass Capacitor Placement for TSSOP and Similar Packages

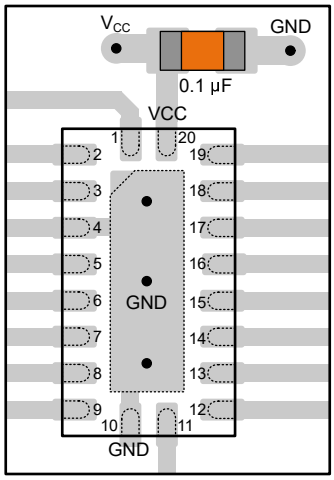


Figure 8-4. Example Bypass Capacitor Placement for WQFN and Similar Packages

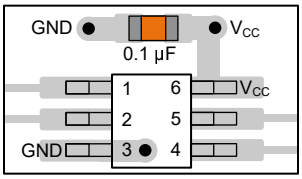


Figure 8-5. Example Bypass Capacitor Placement for SOT, SC70 and Similar Packages

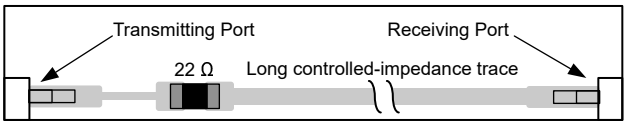


Figure 8-6. Example Damping Resistor Placement for Improved Signal Integrity

9 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation, see the following:

- Texas Instruments, *CMOS Power Consumption and C_{pd} Calculation* application report
- Texas Instruments, *Designing With Logic* application report
- Texas Instruments, *Thermal Characteristics of Standard Linear and Logic (SLL) Packages and Devices* application report

9.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. Click on *Notifications* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

9.3 Support Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

Linked content is provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

9.4 Trademarks

NanoStar™ is a trademark of Texas Instruments.
TI E2E™ is a trademark of Texas Instruments.
All trademarks are the property of their respective owners.

9.5 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

9.6 Glossary

TI Glossary	This glossary lists and explains terms, acronyms, and definitions.

10 Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from Revision C (February 2012) to Revision D (June 2025)	Page
• Added *Package Information* table, *Pin Functions* table, *ESD Ratings* table, *Thermal Information* table, *Device Functional Modes,*Application and Implementation section, *Device and Documentation Support* section, and *Mechanical, Packaging, and Orderable Information* section	1
• Updated operating temperature to 125°C and respective values in *Electrical Characteristics* table, *Recommended Operating Conditions* table, and *Switching Characteristics* tables	1

Changes from Revision B (March 2012) to Revision C (February 2012)	Page
• Updated ORDERING INFORMATION table.	1

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74AUP2G14DCKR	Active	Production	SC70 (DCK) | 6	3000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 125	(H65, H6F)
SN74AUP2G14DCKR.B	Active	Production	SC70 (DCK) | 6	3000 | LARGE T&R	Yes	SN	Level-1-260C-UNLIM	-40 to 85	(H65, H6F)
SN74AUP2G14DCKRG4	Active	Production	SC70 (DCK) | 6	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(H65, H6F)
SN74AUP2G14DCKRG4.B	Active	Production	SC70 (DCK) | 6	3000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	(H65, H6F)
SN74AUP2G14DRYR	Active	Production	SON (DRY) | 6	5000 | LARGE T&R	Yes	NIPDAU | NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DRYR.B	Active	Production	SON (DRY) | 6	5000 | LARGE T&R	Yes	NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DRYRG4	Active	Production	SON (DRY) | 6	5000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DRYRG4.B	Active	Production	SON (DRY) | 6	5000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DSF2	Active	Production	SON (DSF) | 6	5000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DSF2.B	Active	Production	SON (DSF) | 6	5000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DSFR	Active	Production	SON (DSF) | 6	5000 | LARGE T&R	Yes	NIPDAU | NIPDAUAG	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DSFR.B	Active	Production	SON (DSF) | 6	5000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DSFRG4	Active	Production	SON (DSF) | 6	5000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14DSFRG4.B	Active	Production	SON (DSF) | 6	5000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	H6
SN74AUP2G14YFPR	Active	Production	DSBGA (YFP) | 6	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	HFN
SN74AUP2G14YFPR.B	Active	Production	DSBGA (YFP) | 6	3000 | LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	HFN

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

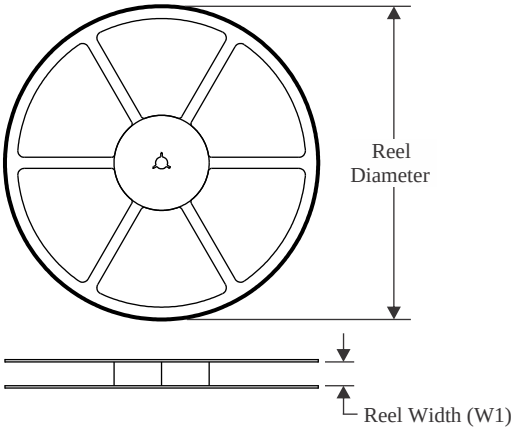
(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

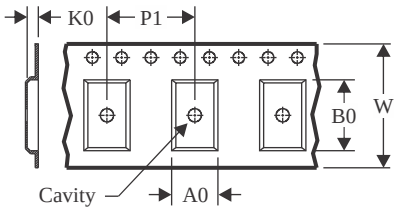
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

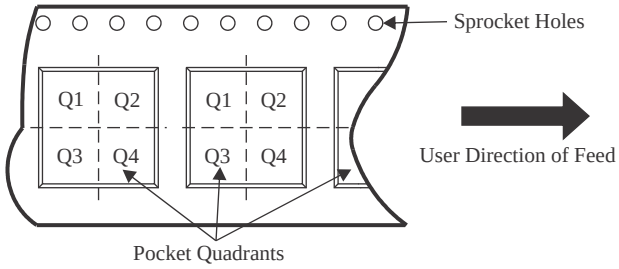


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

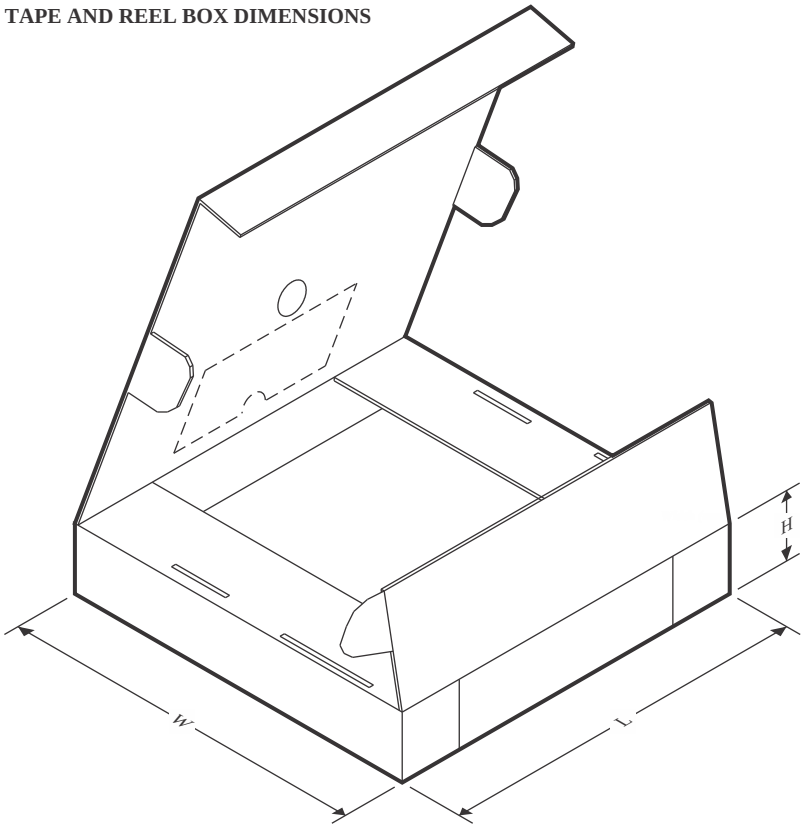
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUP2G14DCKR	SC70	DCK	6	3000	178.0	8.4	2.25	2.45	1.2	4.0	8.0	Q3
SN74AUP2G14DCKRG4	SC70	DCK	6	3000	178.0	9.0	2.4	2.5	1.2	4.0	8.0	Q3
SN74AUP2G14DCKRG4	SC70	DCK	6	3000	178.0	9.2	2.4	2.4	1.22	4.0	8.0	Q3
SN74AUP2G14DRYR	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74AUP2G14DRYRG4	SON	DRY	6	5000	180.0	9.5	1.15	1.6	0.75	4.0	8.0	Q1
SN74AUP2G14DSF2	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.5	4.0	8.0	Q3
SN74AUP2G14DSFR	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.5	4.0	8.0	Q2
SN74AUP2G14DSFRG4	SON	DSF	6	5000	180.0	8.4	1.16	1.16	0.5	4.0	8.0	Q2
SN74AUP2G14YFPR	DSBGA	YFP	6	3000	178.0	9.2	0.89	1.29	0.62	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

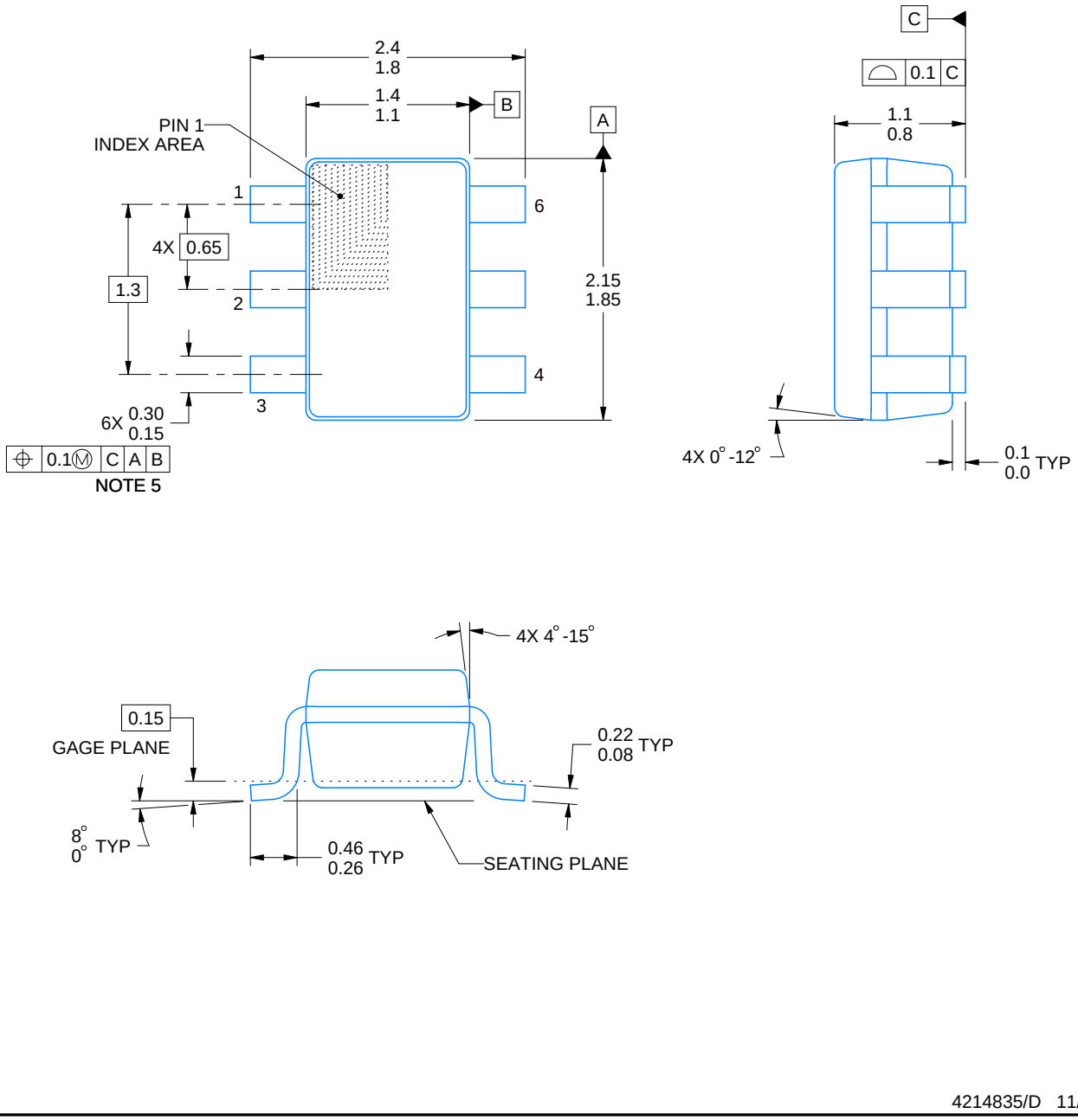
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AUP2G14DCKR	SC70	DCK	6	3000	208.0	191.0	35.0
SN74AUP2G14DCKRG4	SC70	DCK	6	3000	180.0	180.0	18.0
SN74AUP2G14DCKRG4	SC70	DCK	6	3000	180.0	180.0	18.0
SN74AUP2G14DRYR	SON	DRY	6	5000	184.0	184.0	19.0
SN74AUP2G14DRYRG4	SON	DRY	6	5000	184.0	184.0	19.0
SN74AUP2G14DSF2	SON	DSF	6	5000	210.0	185.0	35.0
SN74AUP2G14DSFR	SON	DSF	6	5000	210.0	185.0	35.0
SN74AUP2G14DSFRG4	SON	DSF	6	5000	210.0	185.0	35.0
SN74AUP2G14YFPR	DSBGA	YFP	6	3000	220.0	220.0	35.0

PACKAGE OUTLINE

DCK0006A

SOT - 1.1 max height

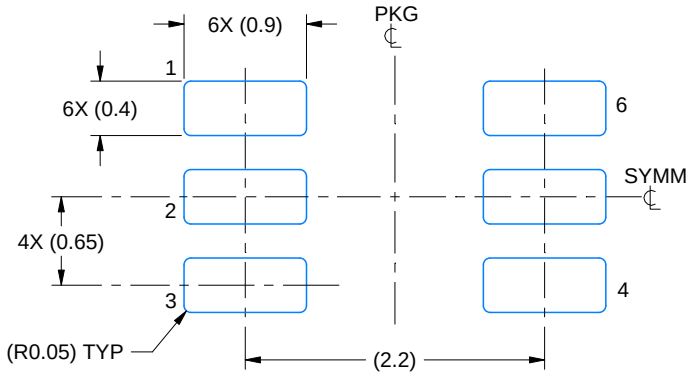
SMALL OUTLINE TRANSISTOR



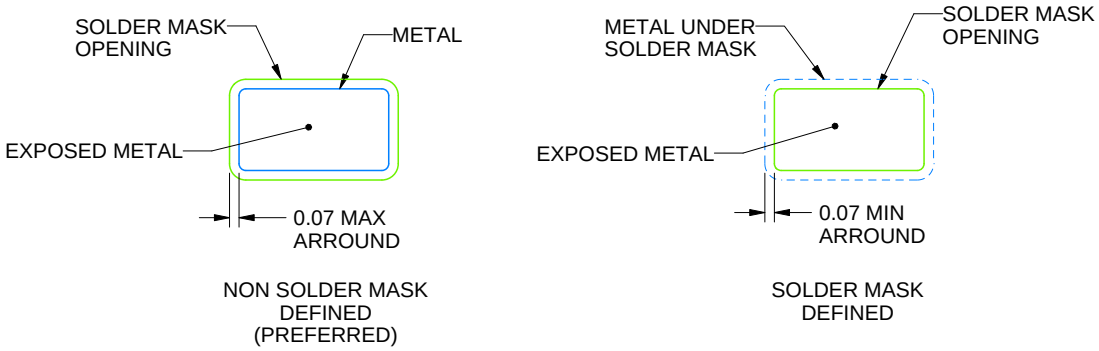
4214835/D 11/2024

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
4. Falls within JEDEC MO-203 variation AB.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X

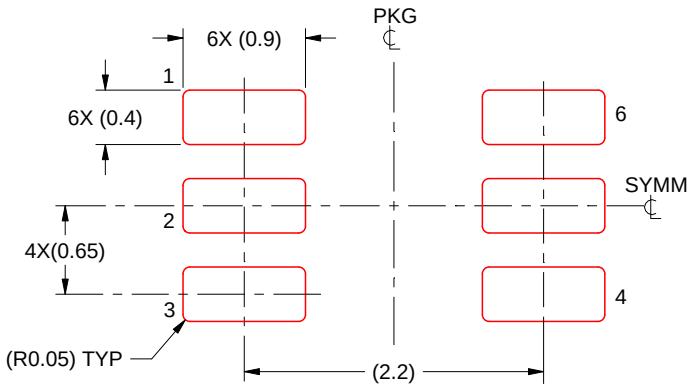


SOLDER MASK DETAILS

4214835/D 11/2024

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:18X

4214835/D 11/2024

NOTES: (continued)

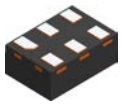
7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

DRY 6 USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

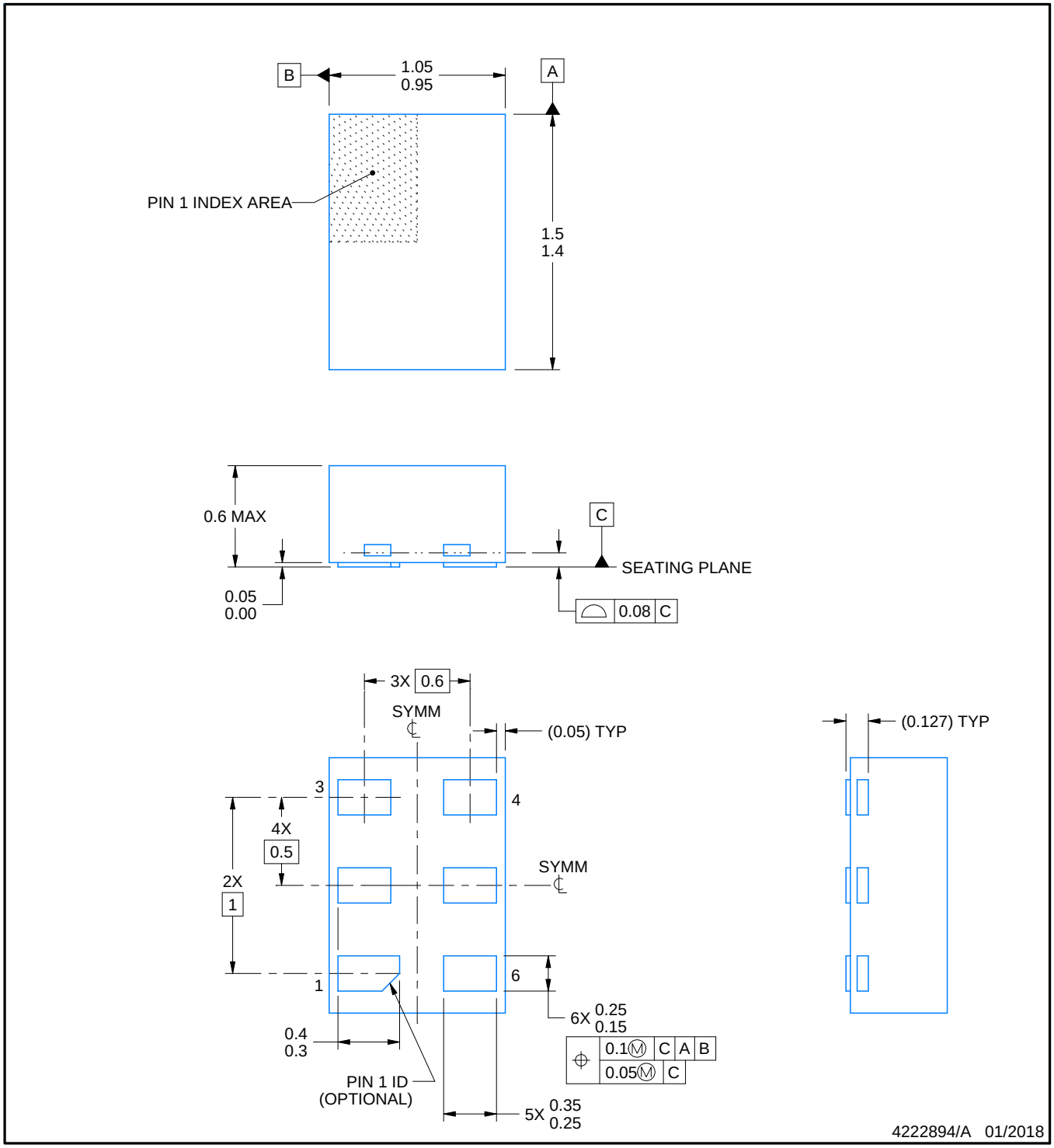
DRY0006A



PACKAGE OUTLINE

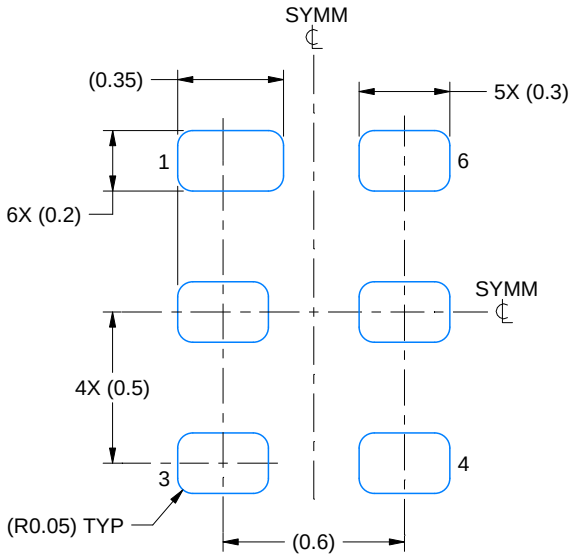
USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

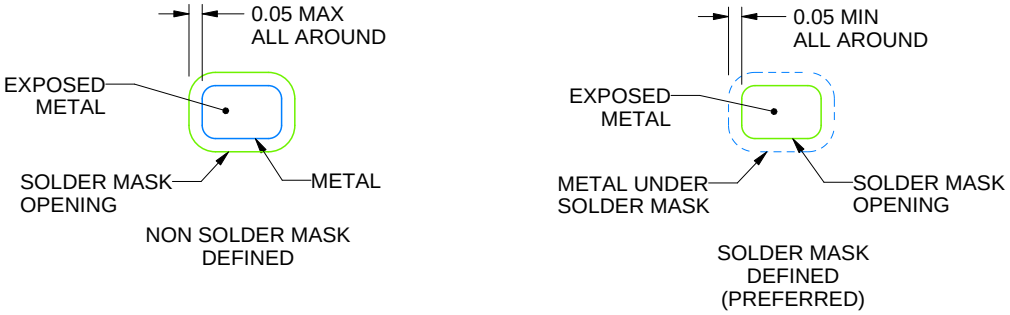


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
1:1 RATIO WITH PKG SOLDER PADS
EXPOSED METAL SHOWN
SCALE:40X



SOLDER MASK DETAILS

4222894/A 01/2018

NOTES: (continued)

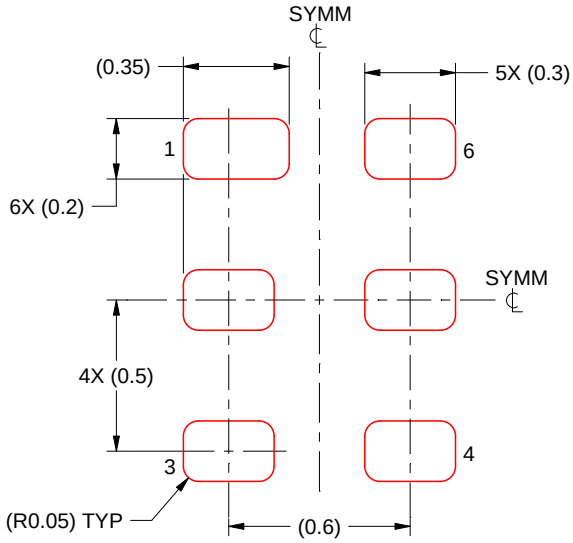
3. For more information, see QFN/SON PCB application report in literature No. SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

DRY0006A

USON - 0.6 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.075 - 0.1 mm THICK STENCIL
SCALE:40X

4222894/A 01/2018

NOTES: (continued)

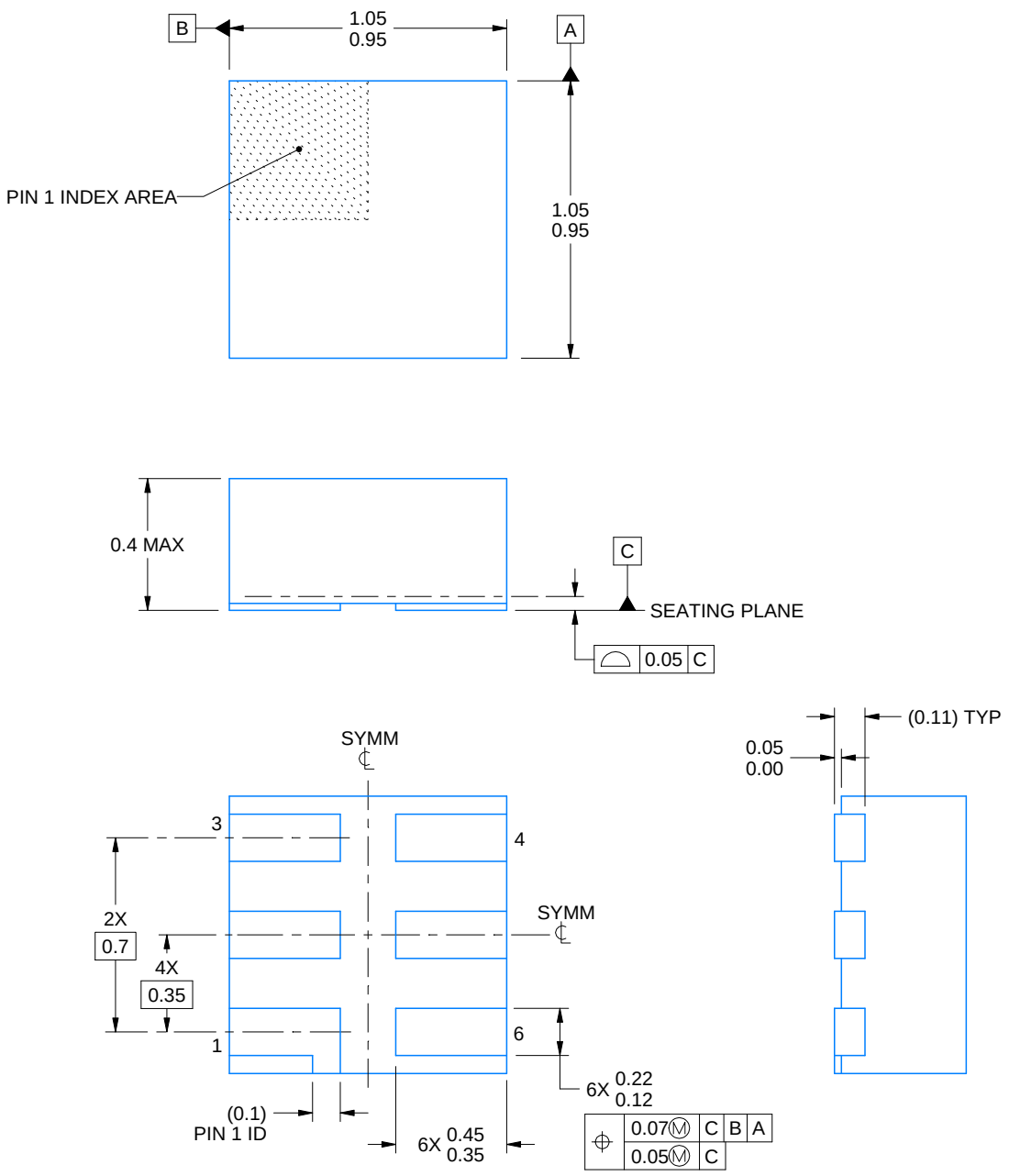
4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGE OUTLINE

DSF0006A

X2SON - 0.4 mm max height

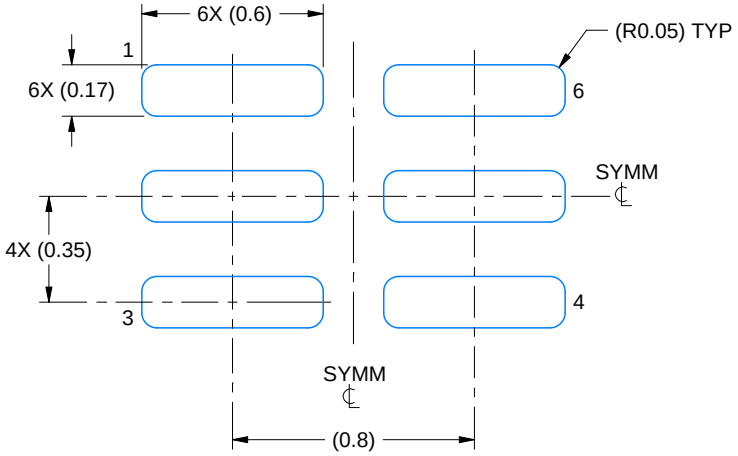
PLASTIC SMALL OUTLINE - NO LEAD



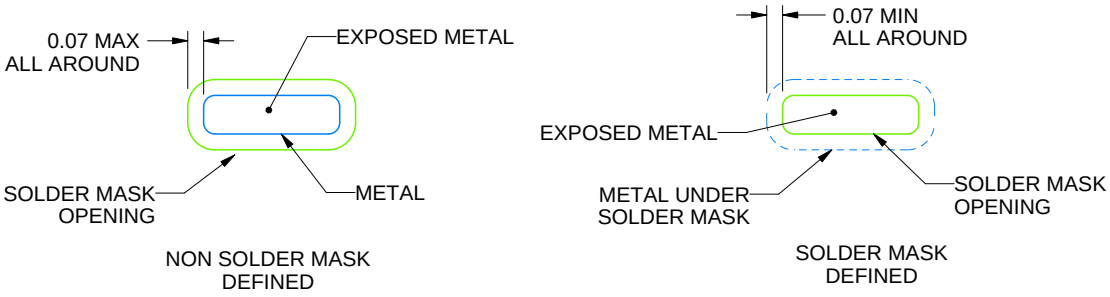
4220597/B 06/2022

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration MO-287, variation X2AAF.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:40X



SOLDER MASK DETAILS

4220597/B 06/2022

NOTES: (continued)

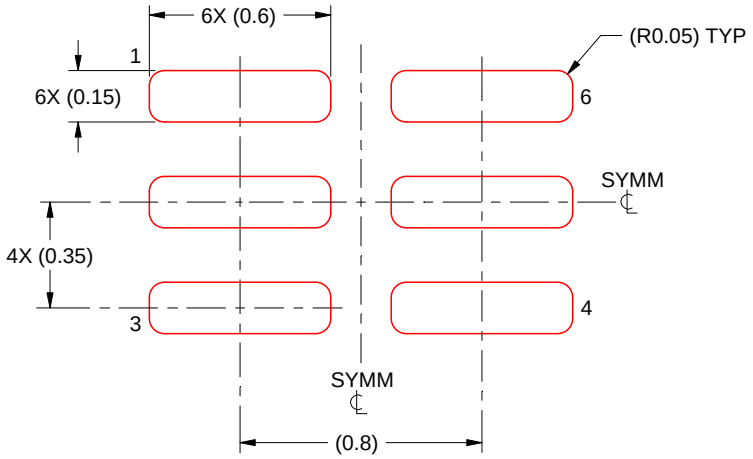
4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

DSF0006A

X2SON - 0.4 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



SOLDER PASTE EXAMPLE
BASED ON 0.09 mm THICK STENCIL

PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:40X

4220597/B 06/2022

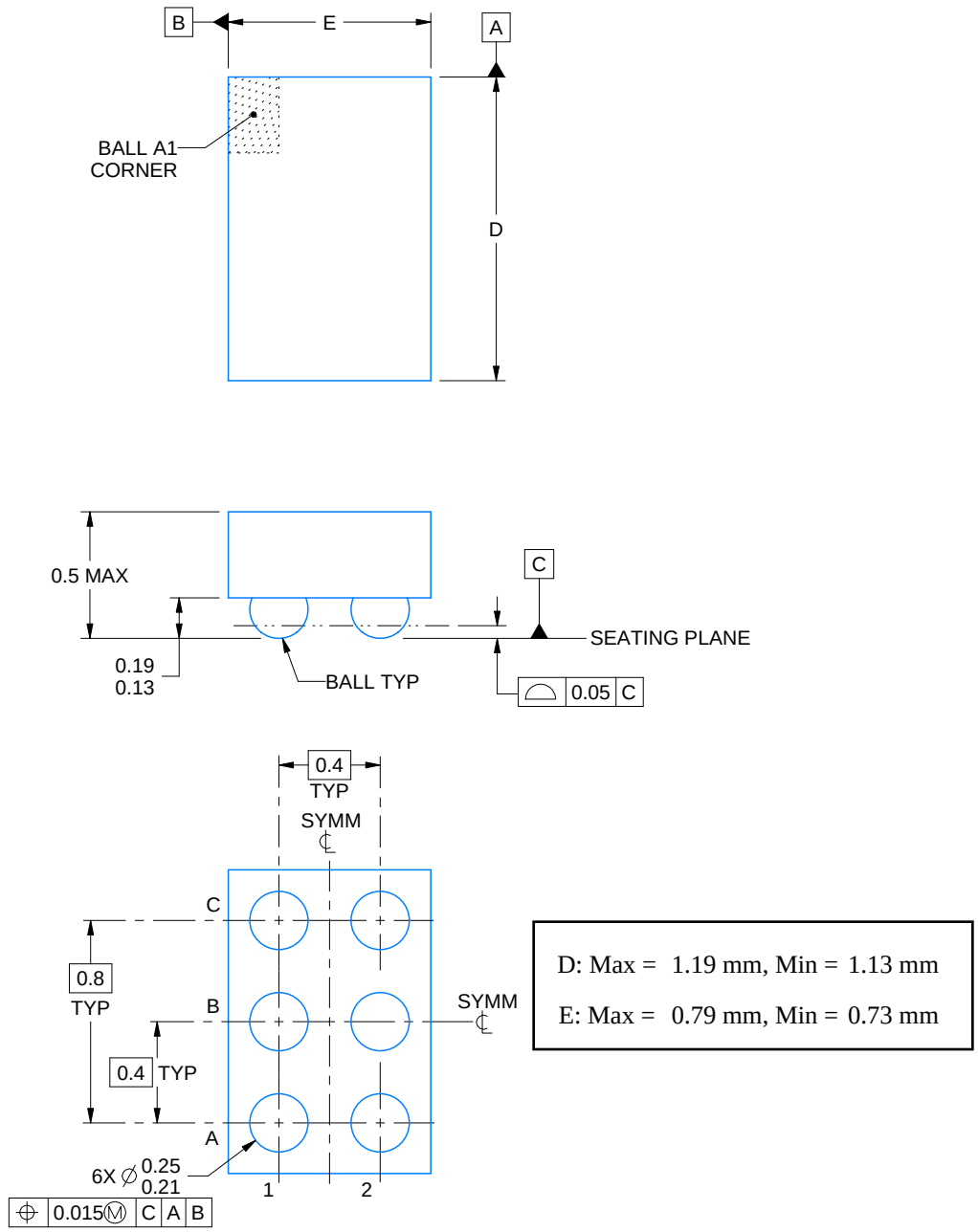
4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

PACKAGE OUTLINE

YFP0006

DSBGA - 0.5 mm max height

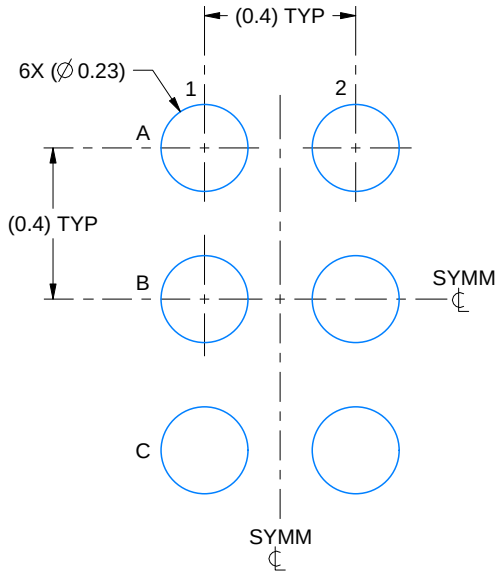
DIE SIZE BALL GRID ARRAY



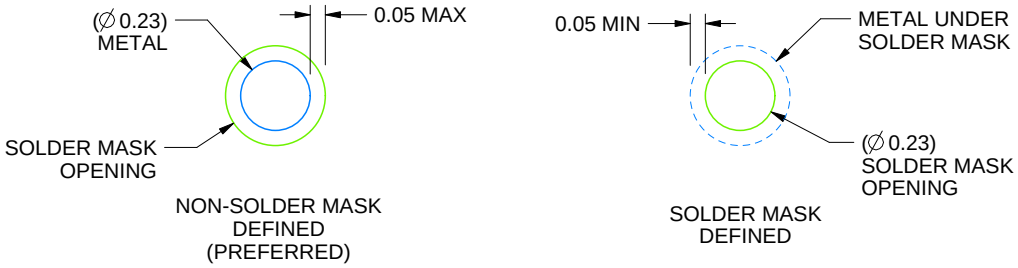
4223410/A 11/2016

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.



LAND PATTERN EXAMPLE
SCALE:50X

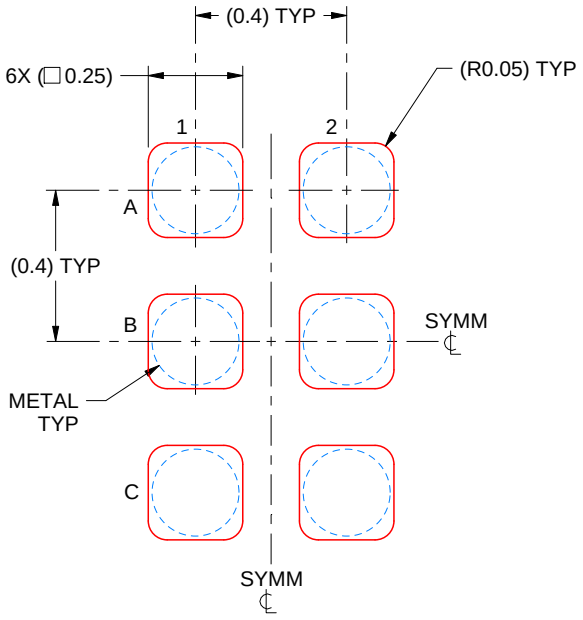


SOLDER MASK DETAILS
NOT TO SCALE

4223410/A 11/2016

NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints.
   For more information, see Texas Instruments literature number SNVA009 (www.ti.com/lit/snva009).



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL
SCALE:50X

4223410/A 11/2016

NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES “AS IS” AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI’s products are provided subject to TI’s Terms of Sale, TI’s General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI’s provision of these resources does not expand or otherwise alter TI’s applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Last updated 10/2025